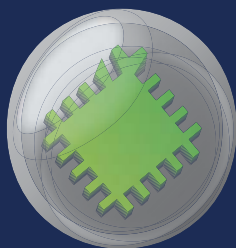


electronic design and evolution fair 2011

設計
進化
新!

Reinvent the Way You Design



edefair

Exhibition Report

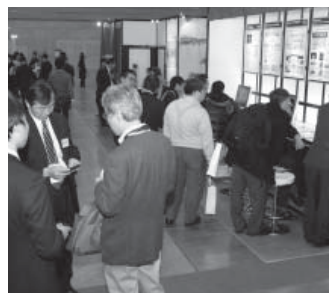
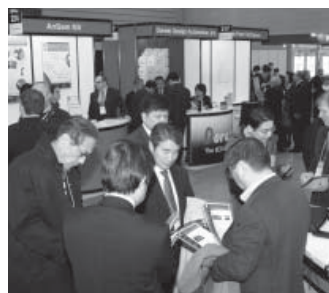
Schedule: Thursday, January 27 - Friday, January 28 2011

Location: Pacifico Yokohama

Sponsor: JEITA Japan Electronics and Information Technology Industries Association

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1. Exhibition Outline

(1) Schedule: Thursday, January 27, 2011 10:00 - 20:00 (18:00 - 20:00 Premium Hour)

Friday, January 28, 2011 10:00 - 18:00 (18:00 - 19:00 Happy Hour)

(2) Location: Pacifico Yokohama (Exhibition Hall, Annex Hall)

(3) Sponsor: Japan Electronics and Information Technology Industries Association (JEITA)

(4) Cooperation: Electronic Design Automation Consortium (EDAC)

(5) Support: Ministry of the Economy, Trade and Industry, Japan (METI)

Embassy of the United States of America in Japan

Distributors Association of Foreign Semiconductors (DAFS)

City of Yokohama (No particular order)

(6) Assistance: Institute of Electronics, Information and Communication Engineers (IEICE)

Information Processing Society of Japan (IPSJ)

Japan Electronics Packaging and Circuits Association (JPCA) (No particular order)

(7) Management: Japan Electronics Show Association (JESA)

(8) Number of Visitors: 8,016 (Previous year: 9,300)

(9) Number of Exhibitors: 118 companies/199 booths (Previous year: 113 companies/231 booths)

(10) Exhibitor Seminars: 82 sessions/2,491 attendees (Previous year: 84 sessions/2,337 attendees)

(11) Suites: 3 companies (Previous year: 4 companies)

(12) University Plaza: 8 universities (Previous year: 9 universities)

(13) Overview:

Sponsored by the Japan Electronics and Information Technology Industries Association (JEITA), the Electronic Design and Solution Fair 2011 (EDSFair2011) was held on January 27th (Thursday) and 28th (Friday), 2011 at Pacifico Yokohama in Japan. This two-day trade show showcased the latest developments in advanced device designing and manufacturing technologies. A total of 118 exhibiting companies and organizations opened 199 booths and attracted 8,016 visitors in the 2 days.

Now in its 11th year, this exhibition aimed to improve the industrial competitiveness of Japan in the midst of fierce international competition. Based on a theme of world-leading "Reinvent the Way You Design", this exhibition showcased new design solutions, and world leading technologies and services aimed at solving a variety of problems including improved performance, cutting risks and costs, conversion to low-power consumption, and global environment conservation along with a variety of conferences.

On the opening day, Mr. Seizo ONOE, SVP and Managing Director of R&D Strategy, NTT DOCOMO, delivered a keynote speech; "Launching LTE, Next Generation Mobile" and attracted more than 200 audiences who listened earnestly to the presentations. In addition to over 80 exhibitors' seminars which enabled visitors to learn the latest technologies' trend, at the special stage, a special session focused on what designers want to know was held in cooperation with System Design Forum to introduce the latest EDA technology and a collaborating session between Designers' Forum of ASP-DAC and EDSFair 2011 was held to learn more about LPC codesign. Each session provided valuable information and attracted a number of visitors. A Place to Catch the Leading-edge Technology Trend was provided.

The Special Zone also showcased topics and the latest in technologies of interest to engineers, which were divided into the following three sectors: the Emerging Company Area offered solutions presented by new venture companies worldwide; the University Plaza provided a venue where universities presented R&D achievements to encourage technological exchanges between industry, academia, and government; and the JEVeC Village was where domestic venture EDA developers gathered to promote technologies and products utilizing the Monozukuri potential of Japanese corporations.

At the 4th Emerging Company Guided Tour, which was expanded its participation companies to both emerging companies in Japan and overseas, the tour guide introduced exhibitors' technologies and solutions which have less access to visitors and helped communications between visitors and exhibitors. It provided a place to find new technologies and solution and attracted more than 30 tour participants in each tour.

Additionally, the EDSFair schedule on January 27th lengthened time slots from 18:00 to 20:00 on 27th, Premium Hour, to create business opportunities for visitors by aggressively pursuing designers who may not come in their office hour. In this hour, Lottery to win iPad with Visitor Stamp Rally, Visitor support service with free Snickers and the Collaborating Session between ASP-DAC 2011 Designers' Forum and EDSFair 2011 were held along with Exhibitors' Booth Events for Premium Hour. Also "EDSFair Happy Hour" was held after the exhibition on Friday, January 28. Despite after the exhibition closed, a number of related people attended this events and a place for exhibitors and visitors to communicate was provided.

3.Exhibitors Alphabetical order

- 104 AET, INC.
- 204 Aldec-Japan K.K.
- 503 ANSYS Japan K.K.
- 101 Apache Design Solutions, KK
- 303 Applistar Corporation
The DINI Group
- 309 AT DESIGN LINKS CORPORATION
Accelicon Technologies, Inc.
- 306 ATopTech Co.,Ltd
- 004 ATRENTA KK
- 102 AWR Japan
- 308 Berkeley Design Automation, Inc.
- 001 Cadence Design Systems, Japan
INNOTECH CORPORATION
ARM K.K.
hd Lab, Inc.
Calypto Design Systems, Inc
CM Engineering Co., Ltd.
Chubu Toshiba Engineering Corporation
TOSHIBA INFORMATION SYSTEMES(JAPAN) CORPORATION
NIPPON SYSTEMWARE CO., LTD.
Magillem Design Services
- 210 CALYPTO DESIGN SYSTEMS, K.K.
- 304 Carbon Design Systems Japan K.K.
- 302 CM Engineering Co., Ltd
- 307 CreDist, Inc.
DELL JAPAN INC.
UnivaUD Japan Office
- 404 CYBERNET SYSTEMS CO., LTD
- 002 CyberTec Inc.
Jasper Design Automation
- 403 EDN Japan
- 105 FORTE DESIGN SYSTEMS
- 209 FUJITSU LIMITED
- 107 INNOTECH CORPORATION
Arteris Inc.
Avalent Technologies, Inc.
Calypto Design Systems, Inc.
Duolog Technologies Ltd.
Jazz Semiconductor, Subsidiary of Tower
MoDeCH Inc.
Target Compiler Technologies N.V.
- 305 Interoperable PDK Alliance
Springsoft, Inc.
Synopsys, Inc.

- 301 IVIS Co., Ltd.
- 311 JEITA ECcenter EDA Standard WG
- 206 Kaimon Co., Ltd.
- 106 KANEMATSU ELECTRONICS LTD.
- 501 MENTOR GRAPHICS JAPAN CO., LTD.
GLOBALFOUNDRIES Japan Ltd.
Semiconductor Manufacturing International(Shanghai) Corp.
ARM K.K
FUJITSU SEMICONDUCTOR LIMITED
National Instruments Japan Corporation
Xilinx K.K.
- 003 MunEDA GmbH
- 401 Nihon EVE K.K.
- 504 Nihon Synopsys G.K.
- 203 Oracle Corporation Japan
- 310 PHYSWARE INC
- 103 PROTOtyping Japan Corp.
IRIS Technologies, Inc.
KaiSemi LTD.
- 208 Pulsic Japan Limited
- 312 Sangyo Times, Inc.
- 502 Semiconductor Technology Academic Research Center
- 207 SPINNAKER SYSTEMS INC.
CAST Inc.
Verific Design Automation Inc.
- 405 SPRINGSOFT K.K.
- 205 TANNER RESEARCH JAPAN K.K.
- 402 TEKLATECH A/S

- JEVeC Village**
- 407 Artgraphics
 - 409 ASTRON. Inc.
 - 408 Gem Design Technologies, Inc.
 - 406 Giga Hertz Technology
Liquid Design Systems Inc.,
 - 313 Japan EDA Venture Consortium (JEVeC)
 - 314 Jedat Inc.
 - 411 Keirex Technology Inc.
Trigence Semiconductor, Inc.
 - 410 Mathematical Systems Inc.
 - 412 TOOL CORPORATION

Emerging Company Area

- 222 AnSem NV
- 215 A-R-Tec Corporation
Kobe University Nagata Lab.
Hiroshima University Yoshida Lab.
- 216 AVERY DESIGN SYSTEMS
- 220 BEEcube Inc.
- 214 Blue Pearl Software
- 218 DOCEA POWER
HD Lab
- 217 Dorado Design Automation, Inc.
- 223 IC Service, Ltd
CMSC, Inc.
IST, Inc.
- 213 ICscape
- 229 Lynguent, Inc.
- 228 NANGATE, INC.
- 219 NextOp Software, Inc.
- 230 POLYTEDA Software Corporation
- 211 REAL INTENT, INC.
- 221 Signal Process Logic Inc.
- 225 Synkom Co.,Ltd.
Micrologic Design Automation
ClioSoft Inc
Amiq EDA
- 212 TOPS Systems Corp.
- 224 Vennsa Technologies, Inc.

University Plaza

- 322 Ehime University Higami and Takahashi Laboratory
- 320 Hiroshima University, Laboratory of Algorithm Engineering
- 321 Kyushu Institute of Technology, Kajihara/Wen Laboratory
- 319 Kyushu Institute of Technology, Nakamura Laboratory
- 316 Nagoya University, Embedded and Real-Time System Laboratory
- 317 Osaka University, Imai and Takeuchi Laboratory
- 315 The University of Aizu, Saito Laboratory
- 318 Tokai University, Shimizu Naohiko Laboratory

*Joint participant company indented

4.Exhibitor Seminar

EDSFair2011 hosted exhibitor seminars for concentrated PR activities targeting limited number of 30 to 100 customers per 45-minute session. The Conference hosted 82 sessions in 9 rooms with 7 tracks by categories.

Number of total Audiences: 2,491

Track Breakdown	No. of Sessions	Jan. 27 Audience	Jan. 28 Audience
ESL	20	87	314
Logic design&Physical design/verification	9	70	307
AMS design·verification/PCB	13	210	106
Functional verification/DFT	18	223	463
LowPower/IP/DFM	13	177	174
Free	5	63	72
Special	4	128	97

5.Suite

Small and medium suites were set up within the Exhibition Hall, providing exhibitors with an undisturbed environment to introduce selected customers to the details of their strategic and not-yet-released products. The suites were also utilized as auseful venue for meetings and negotiations with important customers and a variety of other creative purposes directly related to exhibitors' businesses.

- Suite Exhibitors**
 Cadence Design Systems, Japan
 Nihon Synopsys G.K.
 Lynguent, Inc.

6. Keynote Speech 235 audiences

Launching LTE, Next Generation Mobile

DOCOMO launched LTE in December, 2010. LTE has capability of 300Mbps data speed in the specifications and DOCOMO provided maximum 75Mbps data service at the launch. With the background of a data explosion of mobile communications, many operators are launching or planning commercial LTE in the world. In the presentation, DOCOMO's activities and the global status for LTE were discussed as well as the evolution scenario after LTE.

Mr. Seizo Onoe

SVP and Managing Director of R&D Strategy
NTT DOCOMO, INC.



7. Special Stage

In cooperation with System Design Forum to introduce the latest EDA technology, a special session was held on January 27th. The session consisted of Nano-Scale Physical Design Session and LSI/LPB session from JEITA EDA Technical Committee's Activities and focused on what designers want to know.

In addition, EDSFair prepared for special sessions in collaboration with ASP-DAC 2011 Designers' Forum in time for 16th Asia and South Pacific Design Automation Conference.

On Friday 28th, the Designers' session and Low Power Design Session which were well-received in the previous EDSFair were held this year again. EDSFair offered information and a comprehensive range of projects for engineers from front-line to young, of course, also management positions who are actively involved in ongoing projects.



8. Special Zone

Emerging Company Area 26 companies

Japanese and overseas venture companies brought together the latest information on solutions for speedy uptake by designers and developers at an exhibition booth.

JEVeC Village 11 companies

The members companies of Japan EDA Venture Consortium came together for EDA development to promote their technologies and products which utilizing the Monozukuri potential of Japanese corporations.

University Plaza 8 universities

EDSFair offers an opportunity for university research institutes to present the results of their research projects and to demonstrate achievements in R&D related to design technologies conducted at university institutions while promoting increased collaboration between business and academia.

9. Emerging Company Guided Tour

The expert tour guides at design technology and EDA introduced participant companies' key technologies in Japanese at the special stage then visited their booth to support their presentation and questions and answers.

Tour Schedule

Jan. 27 [THU.]	Jan. 28 [FRI.]	
1st: 14:45-15:55	2nd: 13:00-14:10	3rd: 14:45-15:55
Synkom Co.,Ltd. POLYTEDA Software Corporation IC Service, Ltd Dorado Design Automation, Inc. Interoperable PDK Alliance TEKLATECH A/S	Lynguent, Inc. A-R-Tec Corporation TOPS Systems Corp. Signal Process Logic Inc. Artgraphics Gem Design Technologies Inc.	AVERY DESIGN SYSTEMS Vennsa Technologies, Inc. NextOp Software, Inc. DOCEA POWER REAL INTENT, INC. CM Engineering Co., Ltd

Tour Guide

Jan. 27 [THU.]

Mr. Masami Murakata

Associate General Manager, Development Department-1
STARC (Semiconductor Technology Academic Research Center)



Jan. 28 [FRI.]

Mr. Toshiyasu Akiyama

Department of Industry-Academic Alliance
Innovation Headquarters
Japan Science and Technology Agency



10. Booth Stamp Rally

Visitors participated in lotteries for gifts after collecting any 5 company's stamps. In addition, the lottery to win a Grand Prize was held on January 27 from 19:00 to 20:00

Prize: Gift Card (¥1,000) × **700**

Grand Prize: iPad × **10**

11.Premium Hour Jan. 27 [THU.] 18:00-20:00

■Visitor Support Service

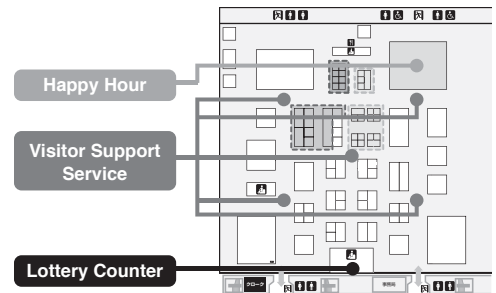
A bar snack offered for free in the Exhibition Hall.

■Lottery to win a Grand Prize

The chance to win a Grand Prize with Booth Stamp Rally was offered only from 19:00 to 20:00.

■Exhibitors' Booth Events

A wide variety of events for visitors were held at exhibitors' booth in the Exhibition Hall.



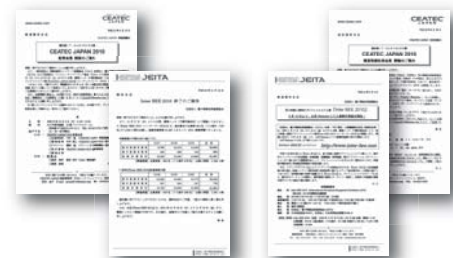
12.EDSFair Happy Hour Jan. 28 [FRI.] 18:00-19:00

This year again, "EDSFair Happy Hour" was held on Friday, January 28 from 18:00 to 19:00. A number of visitors and exhibitors attended this event and made use of this time as a place to have even deeper communication each other once a year.

13.PR Activities

(1)Press Releases

- ①Dissemination of release for commencement of exhibit application period (June 9)
- ②Dissemination of release for commencement of online visitors registration (December 1)
- ③Dissemination of release inviting press coverage and Opening announcement (January 20)
- ④Release of event closing report (January 28)



(2)Press Reception at the Fair

Press room set up and management (January 27 and 28)



(3)Mailings

12 mailings of EDSFair2011 Official News sent to those in our past visitor database and this year's pre-registrants

(4)Creation of PR Tools (printed literature)

- ①Exhibition Guide (Japanese, English)
- ②Guide to the Emerging Company Area (English)
- ③PR leaflet/Envelope (Japanese)
- ④Floor Map (Japanese)



(5)Official Website

①URL

www.edsfair.com

②Outline

This is the official EDSFair website, covering information for exhibitors as well as visitors. Many related people have viewed the website. We have taken steps to further improve the usefulness of the site for exhibitors and visitors by allowing exhibitors to upload exhibit information and their latest releases in real-time, as well as by posting up-to-date industry news.

③Page Views

Total requests for html and other files by site visitors December 1, 2010 to February 28, 2011

④No. of exhibitors' information updated

685 (October 21, 2010 to January 28, 2011)



No. of total site visitors:	127,823
No. of total browsed pag	698,050

14. Number and Profile of Visitors

EDSFair2011 Number of Visitors

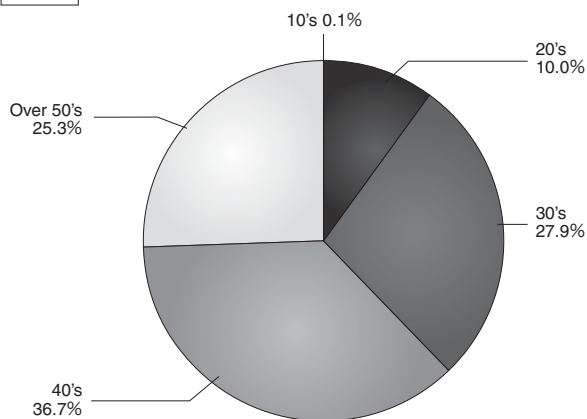
Date	Weather	Number of Visitors
Jan.27	Clear	3,856
Jan.28	Clear	4,160
Total		8,016

Number of Visitors in the past

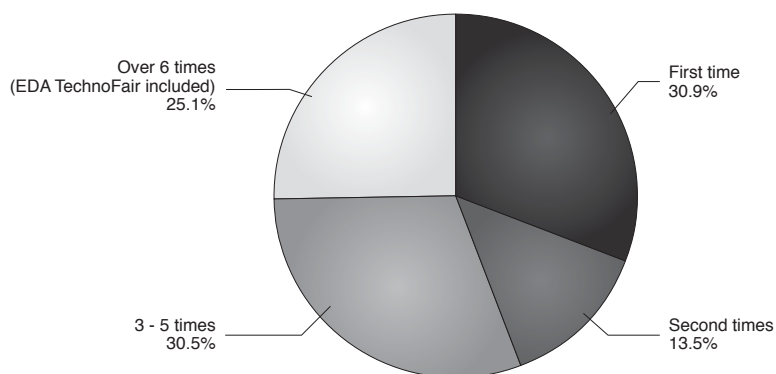
2010	9,300
2009	9,117
2008	10,431

Visitors' Data

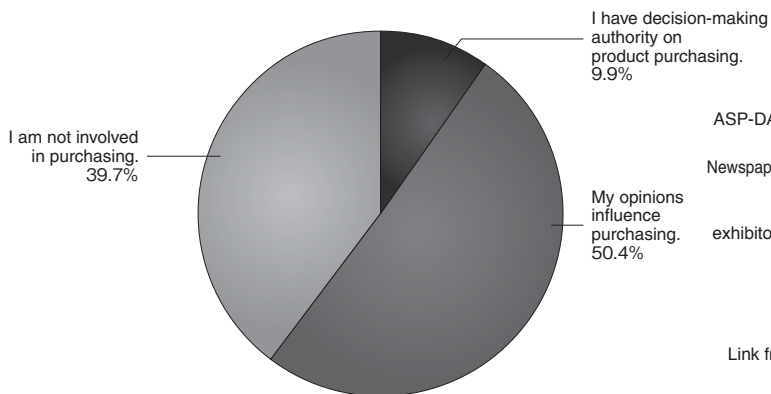
Age



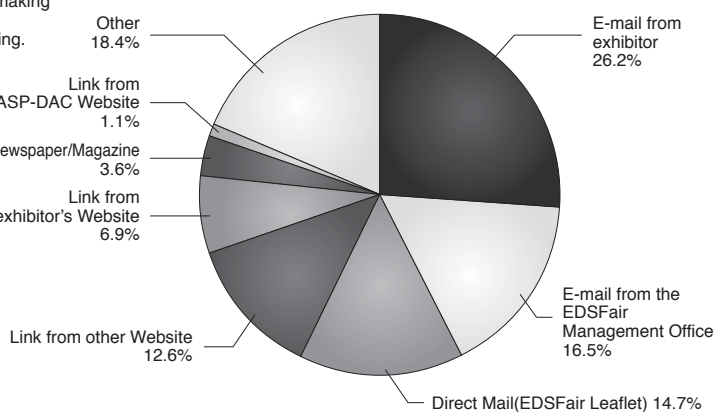
Frequency of Visit



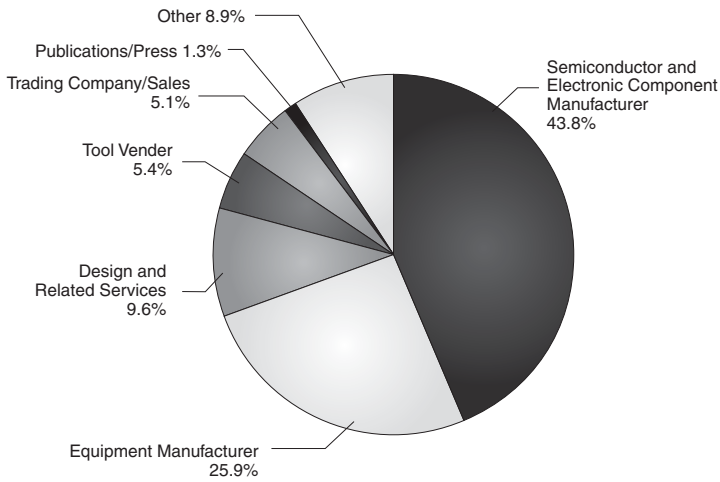
Autuority of Product introduction



How to know Electronic Design and Solution Fair

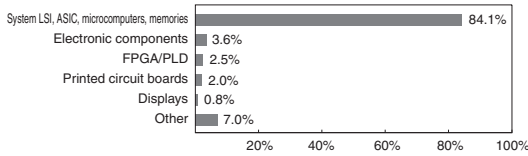


Type of Business

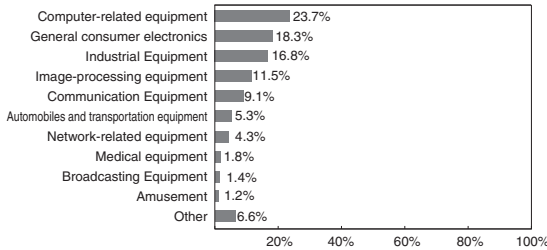


• Details of type of business

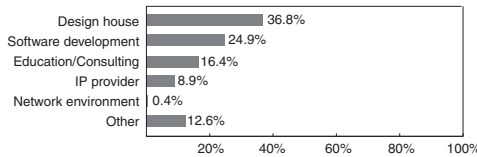
○ Semiconductor and Electronic Component Manufacturer 43.8%



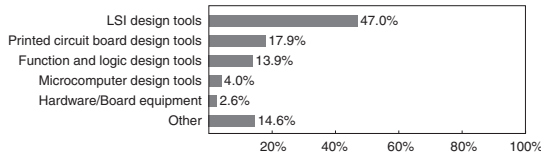
○ Equipment Manufacturer 25.9%



○ Design and Related Services 9.6%

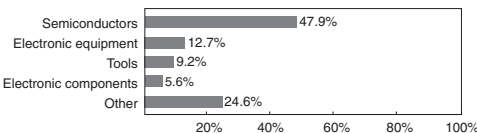


○ Tool Vender 5.4%



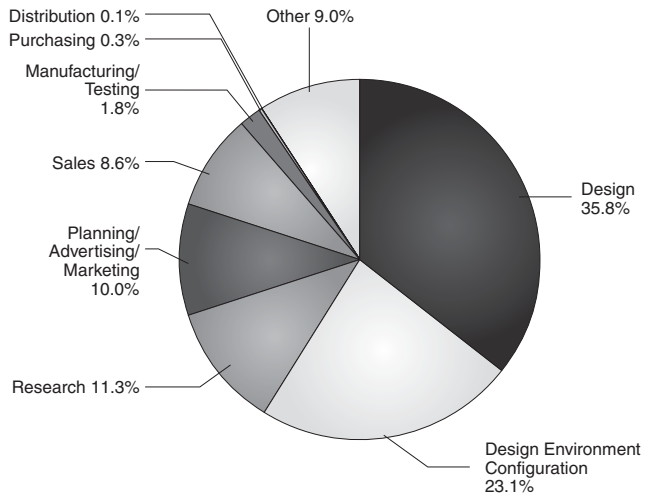
○ Trading Company/Sales 5.1%

*Excluding trade and sales companies to hand tools



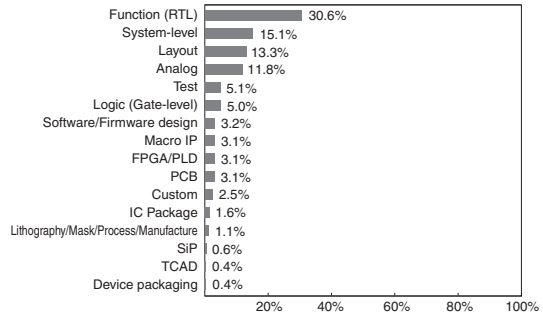
○ Publications/Press 1.3%

Speciality

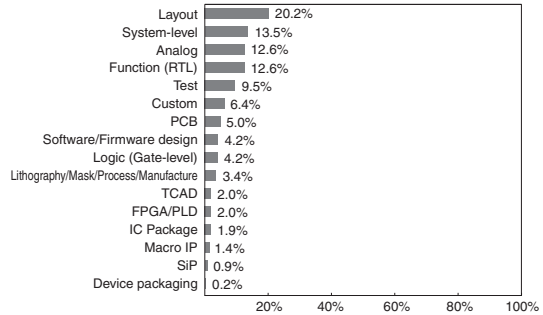


• Details of Speciality

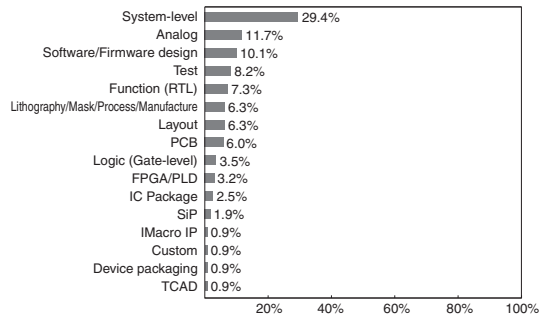
○ Design 35.8%



○ Design Environment Configuration 23.1%



○ Research 11.3%



○ Planning/Advertising/Marketing 10.0%

○ Sales 8.6%

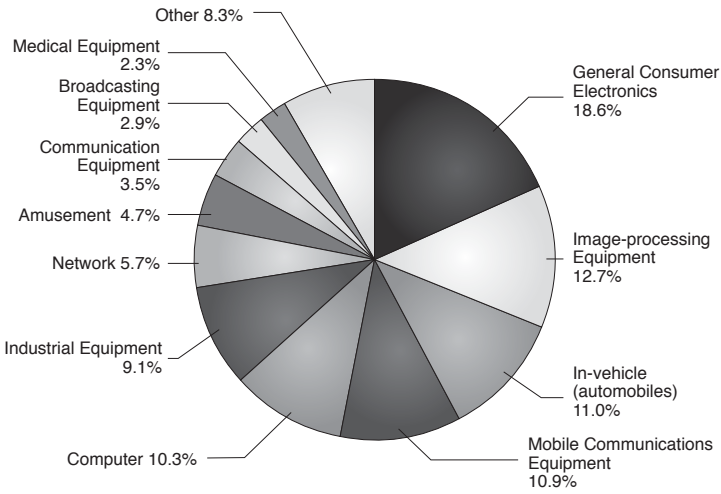
○ Manufacturing/Testing 1.8%

○ Purchasing 0.3%

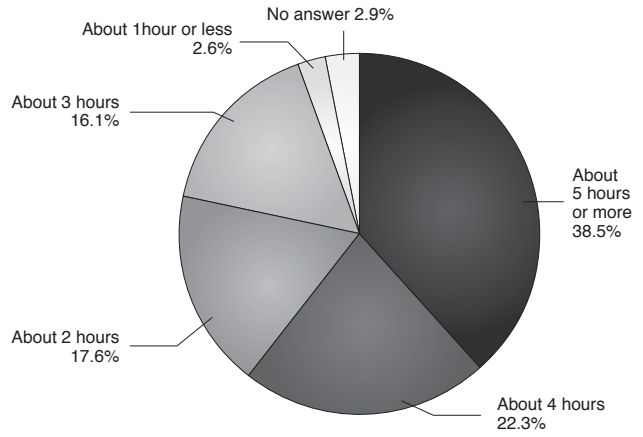
○ Distribution 0.1%

Visitors' Questionnaire Result

Application in charge

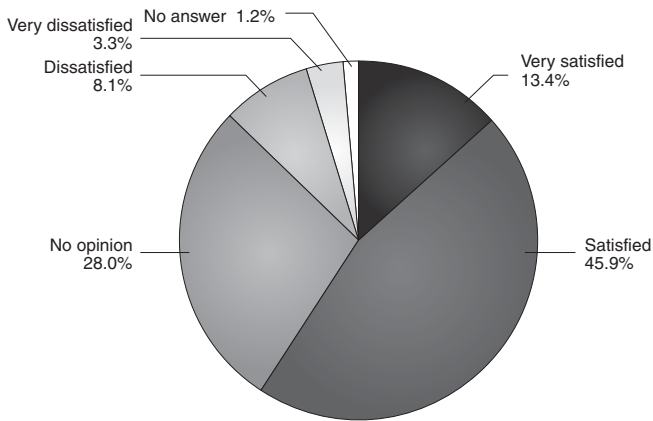


Time spent at the Fair

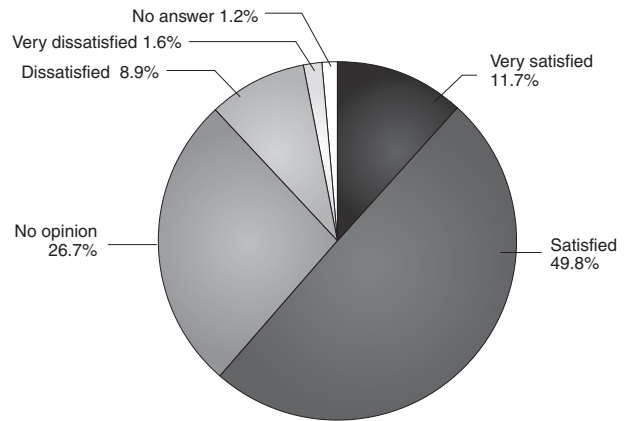


Visitors' Satisfaction

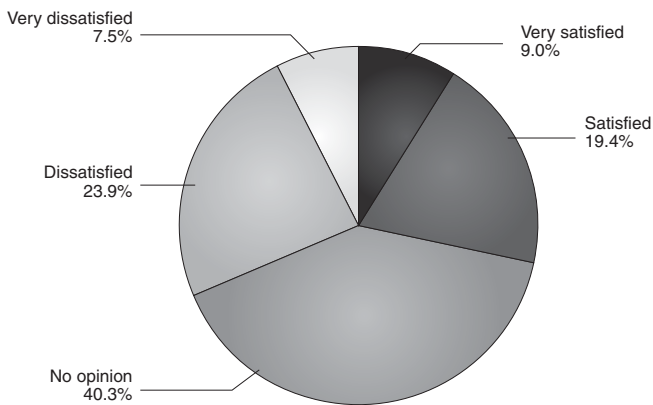
Access to the latest information on products



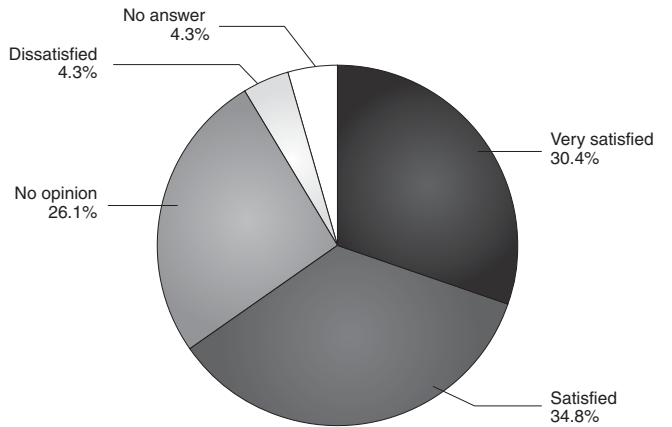
Access to the latest information on design technology and case design



Access to information on competitors



Business negotiations



Sponsor

Japan Electronics and Information Technology Industries Association (JEITA)

5F Ote Center Bldg. , 1-1-3, Otemachi , Chi yoda-ku, Tokyo 100-0004, Japan

<http://www.jeita.or.jp>

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Japan Electronics Show Association (JESA)

12F Ote Center Bldg. , 1-1-3, Otemachi , Chi yoda-ku, Tokyo 100-0004, Japan

TEL: +81-3-6212-5231 FAX: +81-3-6212-5225

Email: info2011@edsfair.com